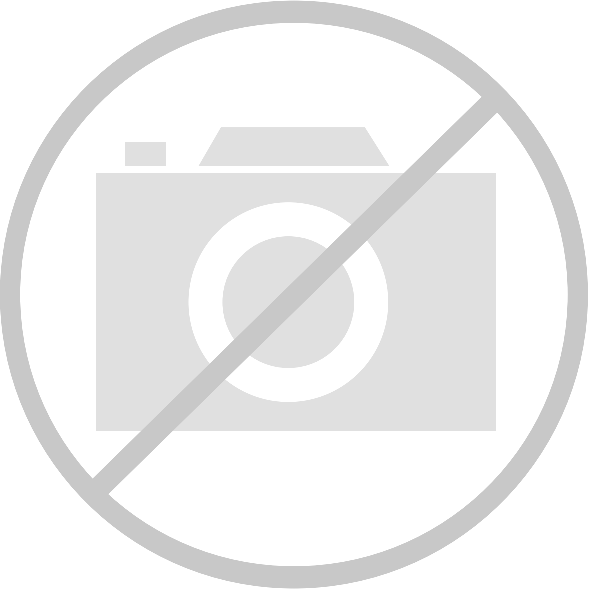
AMD Xilinx - XCV2000E-8FG680C Datasheet



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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications,

Details	
Product Status	Obsolete
Number of LABs/CLBs	9600
Number of Logic Elements/Cells	43200
Total RAM Bits	655360
Number of I/O	512
Number of Gates	2541952
Voltage - Supply	1.71V ~ 1.89V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	680-LBGA Exposed Pad
Supplier Device Package	680-FTEBGA (40x40)
Purchase URL	https://www.e-xfl.com/product-detail/xilinx/xcv2000e-8fg680c

Virtex-E Ordering Information

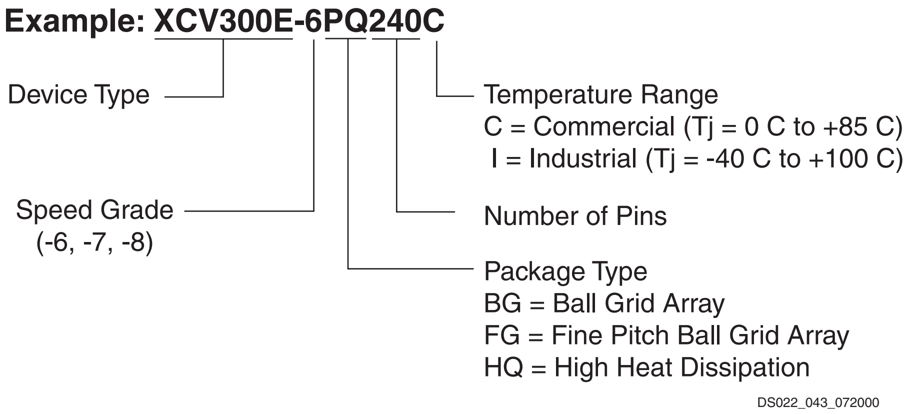

Figure 1: **Ordering Information**

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.
9/20/00	1.7	• Min values added to **Virtex-E Electrical Characteristics** tables. • XCV2600E and XCV3200E numbers added to **Virtex-E Electrical Characteristics** tables (Module 3). • Corrected user I/O count for XCV100E device in Table 1 (Module 1). • Changed several pins to “No Connect in the XCV100E“ and removed duplicate V_{CCINT} pins in Table ~ (Module 4). • Changed pin J10 to “No connect in XCV600E” in Table 74 (Module 4). • Changed pin J30 to “VREF option only in the XCV600E” in Table 74 (Module 4). • Corrected pair 18 in Table 75 (Module 4) to be “AO in the XCV1000E, XCV1600E“.

Date	Version	Revision
11/20/00	1.8	• Upgraded speed grade -8 numbers in **Virtex-E Electrical Characteristics** tables to Preliminary. • Updated minimums in Table 13 and added notes to Table 14. • Added to note 2 to **Absolute Maximum Ratings**. • Changed speed grade -8 numbers for $T_{SHCKO32}$, T_{REG}, T_{BCCS}, and T_{ICKOF}. • Changed all minimum hold times to –0.4 under **Global Clock Setup and Hold for LVTTL Standard, with DLL**. • Revised maximum T_{DLLPW} in -6 speed grade for **DLL Timing Parameters**. • Changed GCLK0 to BA22 for FG860 package in Table 46.
2/12/01	1.9	• Revised footnote for Table 14. • Added numbers to **Virtex-E Electrical Characteristics** tables for XCV1000E and XCV2000E devices. • Updated Table 27 and Table 78 to include values for XCV400E and XCV600E devices. • Revised Table 62 to include pinout information for the XCV400E and XCV600E devices in the BG560 package. • Updated footnotes 1 and 2 for Table 76 to include XCV2600E and XCV3200E devices.
4/2/01	2.0	• Updated numerous values in **Virtex-E Switching Characteristics** tables. • Converted data sheet to modularized format. See the **Virtex-E Data Sheet** section.
10/25/01	2.1	• Updated the **Virtex-E Device/Package Combinations and Maximum I/O** table to show XCV3200E in the FG1156 package.
11/09/01	2.2	• Minor edits.
07/17/02	2.3	• Data sheet designation upgraded from Preliminary to Production.

Virtex-E Data Sheet

The Virtex-E Data Sheet contains the following modules:

- DS022-1, Virtex-E 1.8V FPGAs:
Introduction and Ordering Information (Module 1)
- DS022-2, Virtex-E 1.8V FPGAs:
Functional Description (Module 2)
- DS022-3, Virtex-E 1.8V FPGAs:
DC and Switching Characteristics (Module 3)
- DS022-4, Virtex-E 1.8V FPGAs:
Pinout Tables (Module 4)

Development System

Virtex-E FPGAs are supported by the Xilinx Foundation and Alliance Series CAE tools. The basic methodology for Virtex-E design consists of three interrelated steps: design entry, implementation, and verification. Industry-standard tools are used for design entry and simulation (for example, Synopsys FPGA Express), while Xilinx provides proprietary architecture-specific tools for implementation.

The Xilinx development system is integrated under the Xilinx Design Manager (XDM™) software, providing designers with a common user interface regardless of their choice of entry and verification tools. The XDM software simplifies the selection of implementation options with pull-down menus and on-line help.

Application programs ranging from schematic capture to Placement and Routing (PAR) can be accessed through the XDM software. The program command sequence is generated prior to execution, and stored for documentation.

Several advanced software features facilitate Virtex-E design. RPMs, for example, are schematic-based macros with relative location constraints to guide their placement. They help ensure optimal implementation of common functions.

For HDL design entry, the Xilinx FPGA Foundation development system provides interfaces to the following synthesis design environments.

- Synopsys (FPGA Compiler, FPGA Express)
- Exemplar (Spectrum)
- Synplicity (Synplify)

For schematic design entry, the Xilinx FPGA Foundation and Alliance development system provides interfaces to the following schematic-capture design environments.

- Mentor Graphics V8 (Design Architect, QuickSim II)
- Viewlogic Systems (Viewdraw)

Third-party vendors support many other environments.

A standard interface-file specification, Electronic Design Interchange Format (EDIF), simplifies file transfers into and out of the development system.

Virtex-E FPGAs are supported by a unified library of standard functions. This library contains over 400 primitives and macros, ranging from 2-input AND gates to 16-bit accumulators, and includes arithmetic functions, comparators, counters, data registers, decoders, encoders, I/O functions, latches, Boolean functions, multiplexers, shift registers, and barrel shifters.

The “soft macro” portion of the library contains detailed descriptions of common logic functions, but does not contain any partitioning or placement information. The performance of these macros depends, therefore, on the partitioning and placement obtained during implementation.

RPMs, on the other hand, do contain predetermined partitioning and placement information that permits optimal implementation of these functions. Users can create their own library of soft macros or RPMs based on the macros and primitives in the standard library.

The design environment supports hierarchical design entry, with high-level schematics that comprise major functional blocks, while lower-level schematics define the logic in these blocks. These hierarchical design elements are automatically combined by the implementation tools. Different design entry tools can be combined within a hierarchical design, thus allowing the most convenient entry method to be used for each portion of the design.

Design Implementation

The place-and-route tools (PAR) automatically provide the implementation flow described in this section. The partitioner takes the EDIF net list for the design and maps the logic into the architectural resources of the FPGA (CLBs and IOBs, for example). The placer then determines the best locations for these blocks based on their interconnections and the desired performance. Finally, the router interconnects the blocks.

The PAR algorithms support fully automatic implementation of most designs. For demanding applications, however, the user can exercise various degrees of control over the process. User partitioning, placement, and routing information is optionally specified during the design-entry process. The implementation of highly structured designs can benefit greatly from basic floor planning.

The implementation software incorporates Timing Wizard® timing-driven placement and routing. Designers specify timing requirements along entire paths during design entry. The timing path analysis routines in PAR then recognize these user-specified requirements and accommodate them.

Timing requirements are entered on a schematic in a form directly relating to the system requirements, such as the targeted clock frequency, or the maximum allowable delay between two registers. In this way, the overall performance of the system along entire signal paths is automatically tailored to user-generated specifications. Specific timing information for individual nets is unnecessary.

Design Verification

In addition to conventional software simulation, FPGA users can use in-circuit debugging techniques. Because Xilinx devices are infinitely reprogrammable, designs can be verified in real time without the need for extensive sets of software simulation vectors.

The development system supports both software simulation and in-circuit debugging techniques. For simulation, the system extracts the post-layout timing information from the design database, and back-annotates this information into the net list for use by the simulator. Alternatively, the user can verify timing-critical portions of the design using the TRCE® static timing analyzer.

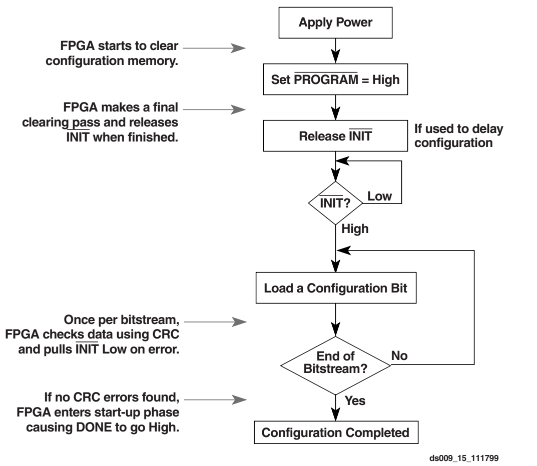
Apply Power
FPGA starts to clear configuration memory.
Set PROGRAM = High
FPGA makes a final clearing pass and releases INIT when finished.
Release INIT
If used to delay configuration
INIT?
Low
High
Load a Configuration Bit
Once per bitstream, FPGA checks data using CRC and pulls INIT Low on error.
End of Bitstream?
No
Yes
If no CRC errors found, FPGA enters start-up phase causing DONE to go High.
Configuration Completed
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Figure 15: **Serial Configuration Flowchart**

Figure 16 shows the timing of master-serial configuration. Master-serial mode is selected by a <000> or <100> on the mode pins (M2, M1, M0). Table 10 shows the timing information for Figure 16.

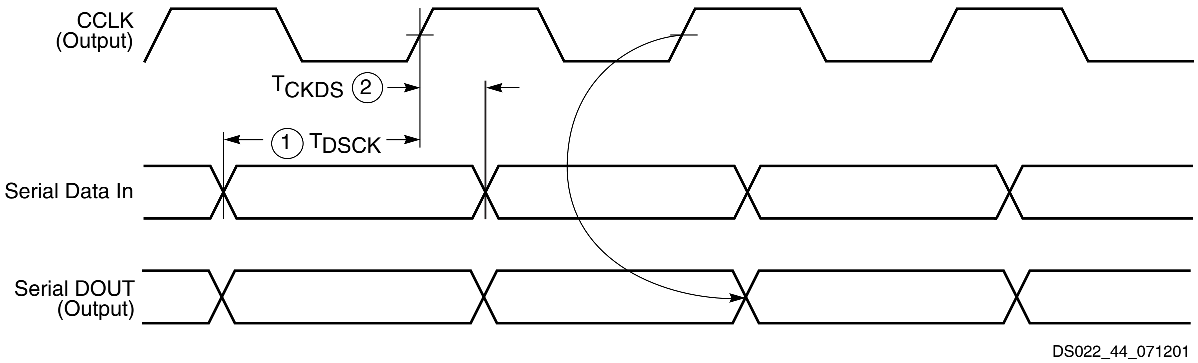

Figure 16: **Master-Serial Mode Programming Switching Characteristics**

At power-up, V_{CC} must rise from 1.0 V to V_{CC} Min in less than 50 ms, otherwise delay configuration by pulling PROGRAM Low until V_{CC} is valid.

SelectMAP Mode

The SelectMAP mode is the fastest configuration option. Byte-wide data is written into the FPGA with a BUSY flag controlling the flow of data.

An external data source provides a byte stream, CCLK, a Chip Select (CS) signal and a Write signal (WRITE). If BUSY is asserted (High) by the FPGA, the data must be held until BUSY goes Low.

Data can also be read using the SelectMAP mode. If WRITE is not asserted, configuration data is read out of the FPGA as part of a readback operation.

After configuration, the pins of the SelectMAP port can be used as additional user I/O. Alternatively, the port can be retained to permit high-speed 8-bit readback.

Retention of the SelectMAP port is selectable on a design-by-design basis when the bitstream is generated. If retention is selected, PROHIBIT constraints are required to prevent the SelectMAP-port pins from being used as user I/O.

Multiple Virtex-E FPGAs can be configured using the SelectMAP mode, and be made to start-up simultaneously. To configure multiple devices in this way, wire the individual CCLK, Data, WRITE, and BUSY pins of all the devices in parallel. The individual devices are loaded separately by asserting the CS pin of each device in turn and writing the appropriate data. See Table 11 for SelectMAP Write Timing Characteristics.

Write

Write operations send packets of configuration data into the FPGA. The sequence of operations for a multi-cycle write operation is shown below. Note that a configuration packet can be split into many such sequences. The packet does not have to complete within one assertion of CS, illustrated in Figure 17.

1. Assert WRITE and CS Low. Note that when CS is asserted on successive CCLKs, WRITE must remain either asserted or de-asserted. Otherwise, an abort is initiated, as described below.
2. Drive data onto D[7:0]. Note that to avoid contention, the data source should not be enabled while CS is Low and WRITE is High. Similarly, while WRITE is High, no more that one CS should be asserted.

3. At the rising edge of CCLK: If BUSY is Low, the data is accepted on this clock. If BUSY is High (from a previous write), the data is not accepted. Acceptance instead occurs on the first clock after BUSY goes Low, and the data must be held until this has happened.
4. Repeat steps 2 and 3 until all the data has been sent.
5. De-assert $\overline{\text{CS}}$ and $\overline{\text{WRITE}}$.

Table 11: **SelectMAP Write Timing Characteristics**

	Description		Symbol		Units
CCLK	D_{0-7} Setup/Hold	1/2	T_{SMDCC}/T_{SMCCD}	5.0 / 1.7	ns, min
	$\overline{\text{CS}}$ Setup/Hold	3/4	T_{SMCSCC}/T_{SMCCCS}	7.0 / 1.7	ns, min
	$\overline{\text{WRITE}}$ Setup/Hold	5/6	T_{SMCCW}/T_{SMWCC}	7.0 / 1.7	ns, min
	BUSY Propagation Delay	7	T_{SMCKBY}	12.0	ns, max
	Maximum Frequency		F_{CC}	66	MHz, max
	Maximum Frequency with no handshake		F_{CCNH}	50	MHz, max

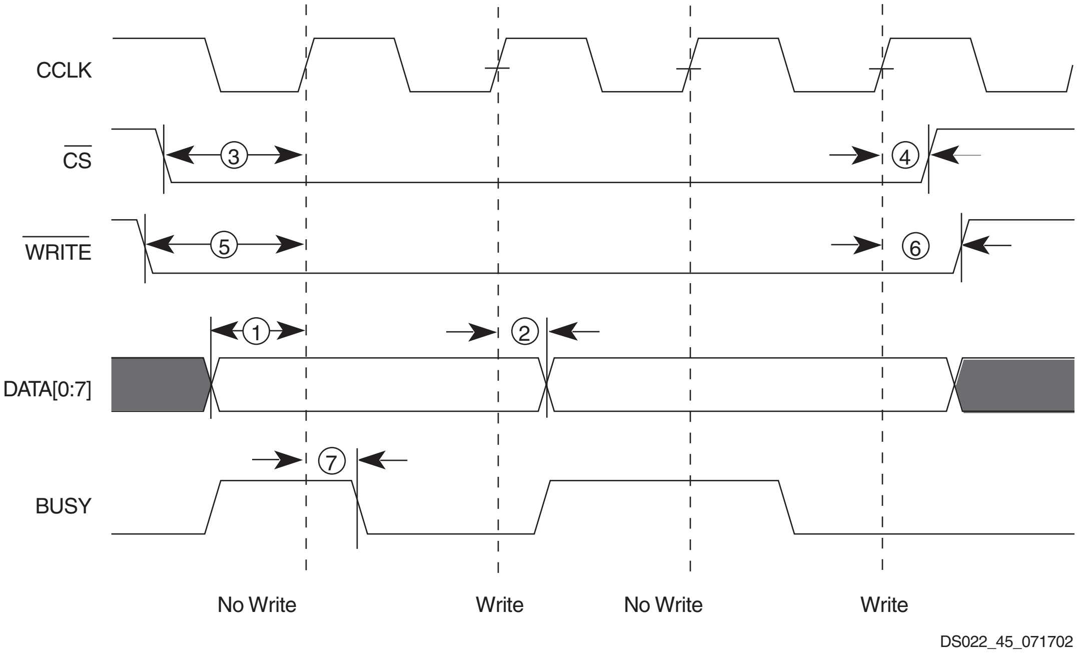

Figure 17: **Write Operations**

A flowchart for the write operation is shown in Figure 18. Note that if CCLK is slower than f_{CCNH}, the FPGA never asserts BUSY, In this case, the above handshake is unnecessary, and data can simply be entered into the FPGA every CCLK cycle.

Abort

During a given assertion of $\overline{\text{CS}}$, the user cannot switch from a write to a read, or vice-versa. This action causes the current packet command to be aborted. The device remains BUSY until the aborted operation has completed. Following an abort, data is assumed to be unaligned to word boundaries, and the FPGA requires a new synchronization word prior to accepting any new packets.

To initiate an abort during a write operation, de-assert $\overline{\text{WRITE}}$. At the rising edge of CCLK, an abort is initiated, as shown in Figure 19.

DLL Properties

Properties provide access to some of the Virtex-E series DLL features, (for example, clock division and duty cycle correction).

Duty Cycle Correction Property

The 1x clock outputs, CLK0, CLK90, CLK180, and CLK270, use the duty-cycle corrected default, exhibiting a 50/50 duty cycle. The DUTY_CYCLE_CORRECTION property (by default TRUE) controls this feature. To deactivate the DLL duty-cycle correction for the 1x clock outputs, attach the DUTY_CYCLE_CORRECTION=FALSE property to the DLL symbol.

Clock Divide Property

The CLKDV_DIVIDE property specifies how the signal on the CLKDV pin is frequency divided with respect to the CLK0 pin. The values allowed for this property are 1.5, 2, 2.5, 3, 4, 5, 8, or 16; the default value is 2.

Startup Delay Property

This property, STARTUP_WAIT, takes on a value of TRUE or FALSE (the default value). When TRUE the device configuration DONE signal waits until the DLL locks before going to High.

Virtex-E DLL Location Constraints

As shown in Figure 26, there are four additional DLLs in the Virtex-E devices, for a total of eight per Virtex-E device. These DLLs are located in silicon, at the top and bottom of the two innermost block SelectRAM columns. The location constraint LOC, attached to the DLL symbol with the identifier DLL0S, DLL0P, DLL1S, DLL1P, DLL2S, DLL2P, DLL3S, or DLL3P, controls the DLL location.

The LOC property uses the following form:

LOC = DLL0P

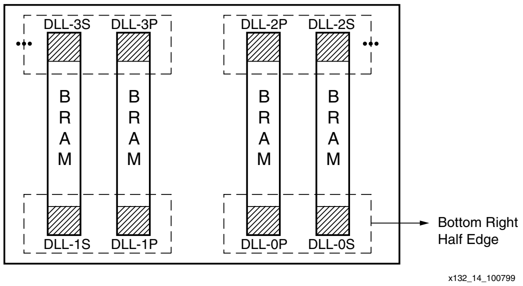

Figure 26: **Virtex Series DLLs**

Design Factors

Use the following design considerations to avoid pitfalls and improve success designing with Xilinx devices.

Input Clock

The output clock signal of a DLL, essentially a delayed version of the input clock signal, reflects any instability on the input clock in the output waveform. For this reason the quality of the DLL input clock relates directly to the quality of the output clock waveforms generated by the DLL. The DLL input clock requirements are specified in the data sheet.

In most systems a crystal oscillator generates the system clock. The DLL can be used with any commercially available quartz crystal oscillator. For example, most crystal oscillators produce an output waveform with a frequency tolerance of 100 PPM, meaning 0.01 percent change in the clock period. The DLL operates reliably on an input waveform with a frequency drift of up to 1 ns — orders of magnitude in excess of that needed to support any crystal oscillator in the industry. However, the cycle-to-cycle jitter must be kept to less than 300 ps in the low frequencies and 150 ps for the high frequencies.

Input Clock Changes

Changing the period of the input clock beyond the maximum drift amount requires a manual reset of the CLKDLL. Failure to reset the DLL produces an unreliable lock signal and output clock.

It is possible to stop the input clock with little impact to the DLL. Stopping the clock should be limited to less than 100 μs to keep device cooling to a minimum. The clock should be stopped during a Low phase, and when restored the full High period should be seen. During this time, LOCKED stays High and remains High when the clock is restored.

When the clock is stopped, one to four more clocks are still observed as the delay line is flushed. When the clock is restarted, the output clocks are not observed for one to four clocks as the delay line is filled. The most common case is two or three clocks.

In a similar manner, a phase shift of the input clock is also possible. The phase shift propagates to the output one to four clocks after the original shift, with no disruption to the CLKDLL control.

Output Clocks

As mentioned earlier in the DLL pin descriptions, some restrictions apply regarding the connectivity of the output pins. The DLL clock outputs can drive an OBUF, a global clock buffer BUFG, or they can route directly to destination clock pins. The only BUFGs that the DLL clock outputs can drive are the two on the same edge of the device (top or bottom). In addition, the CLK2X output of the secondary DLL can connect directly to the CLKIN of the primary DLL in the same quadrant.

Do not use the DLL output clock signals until after activation of the LOCKED signal. Prior to the activation of the LOCKED signal, the DLL output clocks are not valid and can exhibit glitches, spikes, or other spurious movement.

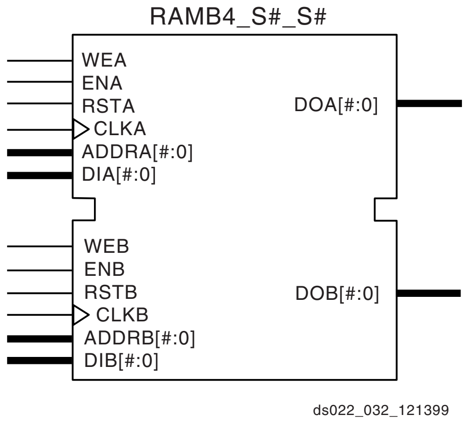

Figure 31: **Dual-Port Block SelectRAM+ Memory**

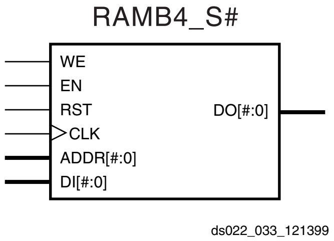

Figure 32: **Single-Port Block SelectRAM+ Memory**

Table 14: **Available Library Primitives**

Primitive	Port A Width	Port B Width
RAMB4_S1	1	N/A
RAMB4_S1_S1		1
RAMB4_S1_S2		2
RAMB4_S1_S4		4
RAMB4_S1_S8		8
RAMB4_S1_S16		16
RAMB4_S2	2	N/A
RAMB4_S2_S2		2
RAMB4_S2_S4		4
RAMB4_S2_S8		8
RAMB4_S2_S16		16
RAMB4_S4	4	N/A
RAMB4_S4_S4		4
RAMB4_S4_S8		8
RAMB4_S4_S16		16
RAMB4_S8	8	N/A
RAMB4_S8_S8		8
RAMB4_S8_S16		16
RAMB4_S16	16	N/A
RAMB4_S16_S16		16

Port Signals

Each block SelectRAM+ port operates independently of the others while accessing the same set of 4096 memory cells.

Table 15 describes the depth and width aspect ratios for the block SelectRAM+ memory.

Table 15: **Block SelectRAM+ Port Aspect Ratios**

Width	Depth	ADDR Bus	Data Bus
1	4096	ADDR<11:0>	DATA<0>
2	2048	ADDR<10:0>	DATA<1:0>
4	1024	ADDR<9:0>	DATA<3:0>
8	512	ADDR<8:0>	DATA<7:0>
16	256	ADDR<7:0>	DATA<15:0>

Clock—CLK[A|B]

Each port is fully synchronous with independent clock pins. All port input pins have setup time referenced to the port CLK pin. The data output bus has a clock-to-out time referenced to the CLK pin.

Enable—EN[A|B]

The enable pin affects the read, write and reset functionality of the port. Ports with an inactive enable pin keep the output pins in the previous state and do not write data to the memory cells.

Write Enable—WE[A|B]

Activating the write enable pin allows the port to write to the memory cells. When active, the contents of the data input bus are written to the RAM at the address pointed to by the address bus, and the new data also reflects on the data out bus. When inactive, a read operation occurs and the contents of the memory cells referenced by the address bus reflect on the data out bus.

Reset—RST[A|B]

The reset pin forces the data output bus latches to zero synchronously. This does not affect the memory cells of the RAM and does not disturb a write operation on the other port.

Address Bus—ADDR[A|B]<#:0>

The address bus selects the memory cells for read or write. The width of the port determines the required width of this bus as shown in Table 15.

Data In Bus—DI[A|B]<#:0>

The data in bus provides the new data value to be written into the RAM. This bus and the port have the same width, as shown in Table 15.

Initialization in Verilog and Synopsys

The block SelectRAM+ structures can be initialized in Verilog for both simulation and synthesis for inclusion in the EDIF output file. The simulation of the Verilog code uses a defparam to pass the initialization. The Synopsys FPGA compiler does not presently support defparam. The initialization values instead attach as attributes to the RAM by a built-in Synopsys dc_script. The translate_off statement stops synthesis translation of the defparam statements. The following code illustrates a module that employs these techniques.

Design Examples

Creating a 32-bit Single-Port RAM

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single port, 128 deep by 32-bit wide RAM to be created using a single block SelectRAM+ cell as shown in Figure 35.

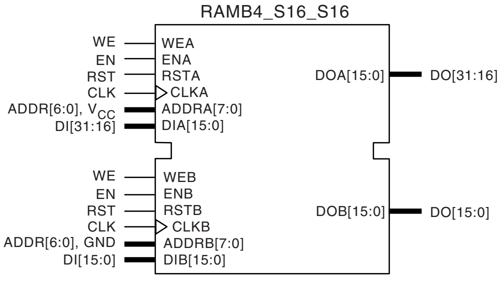

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Figure 35: **Single Port 128 x 32 RAM**

Interleaving the memory space, setting the LSB of the address bus of Port A to 1 (V_{CC}), and the LSB of the address bus of Port B to 0 (GND), allows a 32-bit wide single port RAM to be created.

Creating Two Single-Port RAMs

The true dual-read/write port functionality of the block SelectRAM+ memory allows a single RAM to be split into two single port memories of 2K bits each as shown in Figure 36.

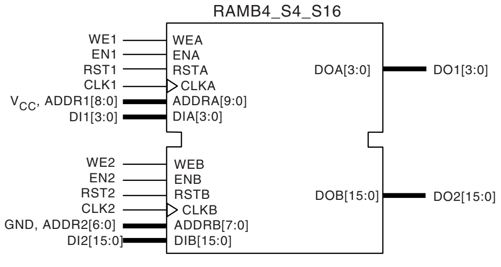

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Figure 36: **512 x 4 RAM and 128 x 16 RAM**

In this example, a 512K x 4 RAM (Port A) and a 128 x 16 RAM (Port B) are created out of a single block SelectRAM+. The address space for the RAM is split by fixing the MSB of Port A to 1 (V_{CC}) for the upper 2K bits and the MSB of Port B to 0 (GND) for the lower 2K bits.

Block Memory Generation

The CoreGen program generates memory structures using the block SelectRAM+ features. This program outputs VHDL or Verilog simulation code templates and an EDIF file for inclusion in a design.

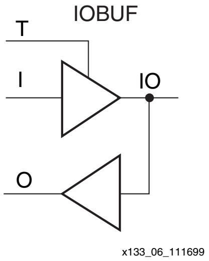

Figure 42: **Input/Output Buffer Symbol (IOBUF)**

The following list details variations of the IOBUF symbol.

- IOBUF
- IOBUF_S_2
- IOBUF_S_4
- IOBUF_S_6
- IOBUF_S_8
- IOBUF_S_12
- IOBUF_S_16
- IOBUF_S_24
- IOBUF_F_2
- IOBUF_F_4
- IOBUF_F_6
- IOBUF_F_8
- IOBUF_F_12
- IOBUF_F_16
- IOBUF_F_24
- IOBUF_LVCMOS2
- IOBUF_PCI33_3
- IOBUF_PCI66_3
- IOBUF_GTL
- IOBUF_GTLP
- IOBUF_HSTL_I
- IOBUF_HSTL_III
- IOBUF_HSTL_IV
- IOBUF_SSTL3_I
- IOBUF_SSTL3_II
- IOBUF_SSTL2_I
- IOBUF_SSTL2_II
- IOBUF_CTT
- IOBUF_AGP
- IOBUF_LVCMOS18
- IOBUF_LVDS
- IOBUF_LVPECL

When the IOBUF symbol used supports an I/O standard that requires a differential amplifier input, the IOBUF automatically configures with a differential amplifier input buffer. The low-voltage I/O standards with a differential amplifier input require an external reference voltage input V_{REF}.

The voltage reference signal is "banked" within the Virtex-E device on a half-edge basis such that for all packages there are eight independent V_{REF} banks internally. See Figure 38, page 34 for a representation of the Virtex-E I/O banks. Within each bank approximately one of every six I/O pins is automatically configured as a V_{REF} input. After placing a differential amplifier input signal within a given V_{REF} bank, the same external source must drive all I/O pins configured as a V_{REF} input.

IOBUF placement restrictions require any differential amplifier input signals within a bank be of the same standard.

The Virtex-E series supports eight banks for the HQ and PQ packages. The CS package supports four V_{CCO} banks.

Additional restrictions on the Virtex-E SelectI/O IOBUF placement require that within a given V_{CCO} bank each IOBUF must share the same output source drive voltage. Input buffers of any type and output buffers that do not require V_{CCO} can be placed within the same V_{CCO} bank. The LOC property can specify a location for the IOBUF.

An optional delay element is associated with the input path in each IOBUF. When the IOBUF drives an input flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Override this default with the NODELAY=TRUE property.

In the case when the IOBUF does not drive an input flip-flop within the IOB, the delay element de-activates by default to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

3-state output buffers and bidirectional buffers can have either a weak pull-up resistor, a weak pull-down resistor, or a weak "keeper" circuit. Control this feature by adding the appropriate symbol to the output net of the IOBUF (PULLUP, PULLDOWN, or KEEPER).

SelectI/O Properties

Access to some of the SelectI/O features (for example, location constraints, input delay, output drive strength, and slew rate) is available through properties associated with these features.

Input Delay Properties

An optional delay element is associated with each IBUF. When the IBUF drives a flip-flop within the IOB, the delay element activates by default to ensure a zero hold-time requirement. Use the NODELAY=TRUE property to override this default.

In the case when the IBUF does not drive a flip-flop within the IOB, the delay element by default de-activates to provide higher performance. To delay the input signal, activate the delay element with the DELAY=TRUE property.

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the global clock buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUFG connection has a net connected to it. Since the N-side IBUFG does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
gclk0_p : IBUFG_LVDS port map
(I=>clk_p_external, O=>clk_internal);

gclk0_n : IBUFG_LVDS port map
(I=>clk_n_external, O=>clk_internal);
```

Verilog Instantiation

```
IBUFG_LVDS gclk0_p (.I(clk_p_external),
.O(clk_internal));

IBUFG_LVDS gclk0_n (.I(clk_n_external),
.O(clk_internal));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET clk_p_external LOC = GCLKPAD3;

NET clk_n_external LOC = C17;
```

GCLKPAD3 can also be replaced with the package pin name, such as D17 for the BG432 package.

Creating LVDS Input Buffers

An LVDS input buffer can be placed in a wide number of IOB locations. The exact location is dependent on the package that is used. The Virtex-E package information lists the possible locations as IO_L#P for the P-side and IO_L#N for the N-side where # is the pair number.

HDL Instantiation

Only one input buffer is required to be instantiated in the design and placed on the correct IO_L#P location. The N-side of the buffer is reserved and no other IOB is allowed to be placed on this location. In the physical device, a configuration option is enabled that routes the pad wire from the IO_L#N IOB to the differential input buffer located in the IO_L#P IOB. The output of this buffer then drives the output of the IO_L#P cell or the input register in the IO_L#P IOB. In EPIC it appears that the second buffer is unused. Any attempt to use this location for another purpose leads to a DRC error in the software.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map (I=>data(0),
O=>data_int(0));
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data[0]),
.O(data_int[0]));
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data<0> LOC = D28; # IO_L0P
```

Optional N-side

Some designers might prefer to also instantiate the N-side buffer for the input buffer. This allows the top-level net list to include net connections for both PCB layout and system-level integration. In this case, only the output P-side IBUF connection has a net connected to it. Since the N-side IBUF does not have a connection in the EDIF net list, it is trimmed from the design in MAP.

VHDL Instantiation

```
data0_p : IBUF_LVDS port map
(I=>data_p(0), O=>data_int(0));

data0_n : IBUF_LVDS port map
(I=>data_n(0), O=>open);
```

Verilog Instantiation

```
IBUF_LVDS data0_p (.I(data_p[0]),
.O(data_int[0]));

IBUF_LVDS data0_n (.I(data_n[0]), .O());
```

Location Constraints

All LVDS buffers must be explicitly placed on a device. For the global clock input buffers this can be done with the following constraint in the .ucf or .ncf file.

```
NET data_p<0> LOC = D28; # IO_L0P

NET data_n<0> LOC = B29; # IO_L0N
```

Adding an Input Register

All LVDS buffers can have an input register in the IOB. The input register is in the P-side IOB only. All the normal IOB register options are available (FD, FDE, FDC, FDCE, FDP, FDPE, FDR, FDRE, FDS, FDSE, LD, LDE, LDC, LDCE, LDP, LDPE). The register elements can be inferred or explicitly instantiated in the HDL code.

The register elements can be packed in the IOB using the IOB property to TRUE on the register or by using the “map -pr [i|o|b]” where “i” is inputs only, “o” is outputs only and “b” is both inputs and outputs.

To improve design coding times VHDL and Verilog synthesis macro libraries available to explicitly create these structures. The input library macros are listed in Table 42. The I and IB inputs to the macros are the external net connections.

Table 44: **Bidirectional I/O Library Macros**

Name	Inputs	Bidirectional	Outputs
IOBUFDS_FD_LVDS	D, T, C	IO, IOB	Q
IOBUFDS_FDE_LVDS	D, T, CE, C	IO, IOB	Q
IOBUFDS_FDC_LVDS	D, T, C, CLR	IO, IOB	Q
IOBUFDS_FDCE_LVDS	D, T, CE, C, CLR	IO, IOB	Q
IOBUFDS_FDP_LVDS	D, T, C, PRE	IO, IOB	Q
IOBUFDS_FDPE_LVDS	D, T, CE, C, PRE	IO, IOB	Q
IOBUFDS_FDR_LVDS	D, T, C, R	IO, IOB	Q
IOBUFDS_FDRE_LVDS	D, T, CE, C, R	IO, IOB	Q
IOBUFDS_FDS_LVDS	D, T, C, S	IO, IOB	Q
IOBUFDS_FDSE_LVDS	D, T, CE, C, S	IO, IOB	Q
IOBUFDS_LD_LVDS	D, T, G	IO, IOB	Q
IOBUFDS_LDE_LVDS	D, T, GE, G	IO, IOB	Q
IOBUFDS_LDC_LVDS	D, T, G, CLR	IO, IOB	Q
IOBUFDS_LDCE_LVDS	D, T, GE, G, CLR	IO, IOB	Q
IOBUFDS_LDP_LVDS	D, T, G, PRE	IO, IOB	Q
IOBUFDS_LDPE_LVDS	D, T, GE, G, PRE	IO, IOB	Q

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
12/7/99	1.0	Initial Xilinx release.
1/10/00	1.1	Re-released with spd.txt v. 1.18, FG860/900/1156 package information, and additional DLL, Select RAM and SelectI/O information.
1/28/00	1.2	Added Delay Measurement Methodology table, updated SelectI/O section, Figures 30, 54, & 55, text explaining Table 5, T_{BYP} values, buffered Hex Line info, p. 8, I/O Timing Measurement notes, notes for Tables 15, 16, and corrected F1156 pinout table footnote references.
2/29/00	1.3	Updated pinout tables, V_{CC} page 20, and corrected Figure 20.
5/23/00	1.4	Correction to table on p. 22.
7/10/00	1.5	• Numerous minor edits. • Data sheet upgraded to Preliminary. • Preview -8 numbers added to **Virtex-E Electrical Characteristics** tables.
8/1/00	1.6	• Reformatted entire document to follow new style guidelines. • Changed speed grade values in tables on pages 35-37.

Calculation of T_{ioop} as a Function of Capacitance

T_{ioop} is the propagation delay from the O Input of the IOB to the pad. The values for T_{ioop} are based on the standard capacitive load (C_{sl}) for each I/O standard as listed in Table 3.

Table 3: **Constants for Use in Calculation of T_{ioop}**

Standard	Csl (pF)	fl (ns/pF)
LVTTL Fast Slew Rate, 2mA drive	35	0.41
LVTTL Fast Slew Rate, 4mA drive	35	0.20
LVTTL Fast Slew Rate, 6mA drive	35	0.13
LVTTL Fast Slew Rate, 8mA drive	35	0.079
LVTTL Fast Slew Rate, 12mA drive	35	0.044
LVTTL Fast Slew Rate, 16mA drive	35	0.043
LVTTL Fast Slew Rate, 24mA drive	35	0.033
LVTTL Slow Slew Rate, 2mA drive	35	0.41
LVTTL Slow Slew Rate, 4mA drive	35	0.20
LVTTL Slow Slew Rate, 6mA drive	35	0.10
LVTTL Slow Slew Rate, 8mA drive	35	0.086
LVTTL Slow Slew Rate, 12mA drive	35	0.058
LVTTL Slow Slew Rate, 16mA drive	35	0.050
LVTTL Slow Slew Rate, 24mA drive	35	0.048
LVCMOS2	35	0.041
LVCMOS18	35	0.050
PCI 33 MHZ 3.3 V	10	0.050
PCI 66 MHz 3.3 V	10	0.033
GTL	0	0.014
GTL+	0	0.017
HSTL Class I	20	0.022
HSTL Class III	20	0.016
HSTL Class IV	20	0.014
SSTL2 Class I	30	0.028
SSTL2 Class II	30	0.016
SSTL3 Class I	30	0.029
SSTL3 Class II	30	0.016
CTT	20	0.035
AGP	10	0.037

Notes:
1. I/O parameter measurements are made with the capacitance values shown above. See the application examples (in Module 2 of this data sheet) for appropriate terminations.
2. I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

For other capacitive loads, use the formulas below to calculate the corresponding T_{ioop}:

$$T_{ioop} = T_{ioop} + T_{opadjust} + (C_{load} - C_{sl}) * fl$$

where:

$T_{opadjust}$ is reported above in the Output Delay Adjustment section.

C_{load} is the capacitive load for the design.

Table 4: **Delay Measurement Methodology**

Standard	V_L[1]	V_H[1]	Meas. Point	V_{REF} (Typ)[2]
LVTTL	0	3	1.4	-
LVCMOS2	0	2.5	1.125	-
PCI33_3	Per PCI Spec			-
PCI66_3	Per PCI Spec			-
GTL	V_{REF} –0.2	V_{REF} +0.2	V_{REF}	0.80
GTL+	V_{REF} –0.2	V_{REF} +0.2	V_{REF}	1.0
HSTL Class I	V_{REF} –0.5	V_{REF} +0.5	V_{REF}	0.75
HSTL Class III	V_{REF} –0.5	V_{REF} +0.5	V_{REF}	0.90
HSTL Class IV	V_{REF} –0.5	V_{REF} +0.5	V_{REF}	0.90
SSTL3 I & II	V_{REF} –1.0	V_{REF} +1.0	V_{REF}	1.5
SSTL2 I & II	V_{REF} –0.75	V_{REF} +0.75	V_{REF}	1.25
CTT	V_{REF} –0.2	V_{REF} +0.2	V_{REF}	1.5
AGP	V_{REF} – ($0.2xV_{CCO}$)	V_{REF} + ($0.2xV_{CCO}$)	V_{REF}	Per AGP Spec
LVDS	1.2 –0.125	1.2 + 0.125	1.2	
LVPECL	1.6 –0.3	1.6 + 0.3	1.6	

Notes:
1. Input waveform switches between V_L and V_H.
2. Measurements are made at V_{REF} (Typ), Maximum, and Minimum. Worst-case values are reported.

   I/O parameter measurements are made with the capacitance values shown in Table 3. See the application examples (in Module 2 of this data sheet) for appropriate terminations.

   I/O standard measurements are reflected in the IBIS model information except where the IBIS format precludes it.

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P137	VCCINT	NA
P104	VCCINT	NA
P88	VCCINT	NA
P77	VCCINT	NA
P43	VCCINT	NA
P32	VCCINT	NA
P16	VCCINT	NA
P240	VCCO	7
P232	VCCO	0
P226	VCCO	0
P212	VCCO	0
P207	VCCO	1
P197	VCCO	1
P180	VCCO	1
P176	VCCO	2
P165	VCCO	2
P150	VCCO	2
P146	VCCO	3
P136	VCCO	3
P121	VCCO	3
P116	VCCO	4
P105	VCCO	4
P90	VCCO	4
P85	VCCO	5
P76	VCCO	5
P61	VCCO	5
P55	VCCO	6
P44	VCCO	6
P30	VCCO	6
P25	VCCO	7
P15	VCCO	7
P233	GND	NA
P227	GND	NA

Table 6: **PQ240 — XCV50E, XCV100E, XCV200E, XCV300E, XCV400E**

Pin #	Pin Description	Bank
P219	GND	NA
P211	GND	NA
P204	GND	NA
P196	GND	NA
P190	GND	NA
P182	GND	NA
P172	GND	NA
P166	GND	NA
P158	GND	NA
P151	GND	NA
P143	GND	NA
P135	GND	NA
P129	GND	NA
P119	GND	NA
P112	GND	NA
P106	GND	NA
P98	GND	NA
P91	GND	NA
P83	GND	NA
P75	GND	NA
P69	GND	NA
P59	GND	NA
P51	GND	NA
P45	GND	NA
P37	GND	NA
P29	GND	NA
P22	GND	NA
P14	GND	NA
P8	GND	NA
P1	GND	NA

Notes:

1. V_{REF} or I/O option only in the XCV100E, 200E, 300E, 400E; otherwise, I/O option only.
2. V_{REF} or I/O option only in the XCV200E, 300E, 400E; otherwise, I/O option only.
3. V_{REF} or I/O option only in the XCV400E; otherwise, I/O option only.

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P210	GCK2	1
P209	IO_LVDS_DLL_L6P	1
P208	IO_VREF	1
P207	VCCO	1
P206	IO_L7N_Y	1
P205	IO_VREF_L7P_Y	1
P204	GND	NA
P203	IO_L8N_Y	1
P202	IO_L8P_Y	1
P201[1]	IO_VREF	1
P200	IO_L9N_YY	1
P199	IO_L9P_YY	1
P198	VCCINT	NA
P197	VCCO	1
P196	GND	NA
P195	IO_L10N_YY	1
P194	IO_VREF_L10P_YY	1
P193	IO_VREF	1
P192	IO_L11N_YY	1
P191	IO_VREF_L11P_YY	1
P190	GND	NA
P189	IO_L12N_YY	1
P188	IO_L12P_YY	1
P187	IO_VREF_L13N	1
P186	IO_L13P	1
P185	IO_WRITE_L14N_YY	1
P184	IO_CS_L14P_YY	1
P183	TDI	NA
P182	GND	NA
P181	TDO	2
P180	VCCO	1
P179	CCLK	2
P178	IO_DOUT_BUSY_L15P_YY	2
P177	IO_DIN_D0_L15N_YY	2
P176	VCCO	2
P175	IO_VREF	2

Table 8: **HQ240 — XCV600E, XCV1000E**

Pin #	Pin Description	Bank
P174	IO_L16P_Y	2
P173	IO_L16N_Y	2
P172	GND	NA
P171	IO_VREF_L17P_Y	2
P170	IO_L17N_Y	2
P169	IO_VREF	2
P168	IO_VREF_L18P_Y	2
P167	IO_D1_L18N_Y	2
P166	GND	NA
P165	VCCO	2
P164	VCCINT	NA
P163	IO_D2_L19P_YY	2
P162	IO_L19N_YY	2
P161[1]	IO_VREF	2
P160	IO_L20P_Y	2
P159	IO_L20N_Y	2
P158	GND	NA
P157	IO_VREF_L21P_Y	2
P156	IO_D3_L21N_Y	2
P155	IO_L22P_Y	2
P154	IO_VREF_L22N_Y	2
P153	IO_L23P_YY	2
P152	IO_L23N_YY	2
P151	GND	NA
P150	VCCO	2
P149	IO	3
P148	VCCINT	NA
P147	IO_VREF	3
P146	VCCO	3
P145	IO_D4_L24P_Y	3
P144	IO_VREF_L24N_Y	3
P143	GND	NA
P142	IO_L25P_Y	3
P141	IO_L25N_Y	3
P140[1]	IO_VREF	3
P139	IO_L26P_YY	3

Table 14: **BG560 — XCV400E, XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin#	See Note
5	IO_L136P_Y	AM31	
5	IO_VREF_L136N_Y	AK28	3
6	IO	AE33	
6	IO	AF31	
6	IO	AJ32	
6	IO	AL33	
6	IO_L137N_YY	AH29	
6	IO_L137P_YY	AJ30	
6	IO_L138N_Y	AK31	
6	IO_VREF_L138P_Y	AH30	3
6	IO_L139N_Y	AG29	
6	IO_L139P_Y	AJ31	
6	IO_VREF_L140N_Y	AK32	
6	IO_L140P_Y	AG30	
6	IO_L141N_Y	AH31	
6	IO_L141P_Y	AF29	
6	IO_L142N_Y	AH32	
6	IO_L142P_Y	AF30	
6	IO_VREF_L143N_YY	AE29	
6	IO_L143P_YY	AH33	
6	IO_L144N_Y	AG33	
6	IO_VREF_L144P_Y	AE30	1
6	IO_L145N_Y	AD29	
6	IO_L145P_Y	AF32	
6	IO_VREF_L146N_Y	AE31	4
6	IO_L146P_Y	AD30	
6	IO_L147N_Y	AE32	
6	IO_L147P_Y	AC29	
6	IO_VREF_L148N_YY	AD31	
6	IO_L148P_YY	AC30	
6	IO_L149N_YY	AB29	
6	IO_L149P_YY	AC31	
6	IO_L150N_Y	AC33	
6	IO_L150P_Y	AB30	
6	IO_L151N_Y	AB31	
6	IO_L151P_Y	AA29	
6	IO_VREF_L152N_Y	AA30	3
6	IO_L152P_Y	AA31	
6	IO_L153N_Y	AA32	
6	IO_L153P_Y	Y29	
6	IO_L154N_Y	AA33	
6	IO_L154P_Y	Y30	
6	IO_VREF_L155N_YY	Y32	
6	IO_L155P_YY	W29	
6	IO_L156N_Y	W30	
6	IO_L156P_Y	W31	
6	IO_L157N_Y	W33	
6	IO_L157P_Y	V30	
6	IO_VREF_L158N_Y	V29	
6	IO_L158P_Y	V31	
6	IO_L159N_Y	V32	
6	IO_VREF_L159P_Y	U33	2
6	IO	U29	
7	IO	E30	
7	IO	F29	
7	IO	F33	
7	IO	G30	
7	IO	K30	
7	IO_L160N_YY	U31	
7	IO_L160P_YY	U32	
7	IO_VREF_L161N_Y	T32	2
7	IO_L161P_Y	T30	
7	IO_L162N_Y	T29	
7	IO_VREF_L162P_Y	T31	
7	IO_L163N_Y	R33	
7	IO_L163P_Y	R31	
7	IO_L164N_Y	R30	
7	IO_L164P_Y	R29	

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
0	IO_L9N	A7
0	IO_L9P	D9
0	IO_L10N	B8
0	IO_VREF_L10P	G10
0	IO_L11N_YY	C9
0	IO_L11P_YY	F10
0	IO_L12N_Y	A8
0	IO_L12P_Y	E10
0	IO_L13N_YY	G11
0	IO_L13P_YY	D10
0	IO_L14N_YY	B10
0	IO_L14P_YY	F11
0	IO_L15N	C10
0	IO_L15P	E11
0	IO_L16N_YY	G12
0	IO_L16P_YY	D11
0	IO_VREF_L17N_YY	C11
0	IO_L17P_YY	F12
0	IO_L18N_YY	A11
0	IO_L18P_YY	E12
0	IO_L19N_Y	D12
0	IO_L19P_Y	C12
0	IO_VREF_L20N_Y	A12
0	IO_L20P_Y	H13
0	IO_LVDS_DLL_L21N	B13
1	GCK2	C13
1	IO	A13[1]
1	IO	A16[1]
1	IO	A19
1	IO	A20
1	IO	A22
1	IO	A24[1]
1	IO	B15[1]
1	IO	B17[1]
1	IO	B23
1	IO_LVDS_DLL_L21P	F14
1	IO_L22N	E14
1	IO_L22P	F13
1	IO_L23N_Y	D14
1	IO_VREF_L23P_Y	A14
1	IO_L24N_Y	C14
1	IO_L24P_Y	H14
1	IO_L25N_YY	G14
1	IO_L25P_YY	C15
1	IO_L26N_YY	E15
1	IO_VREF_L26P_YY	D15
1	IO_L27N_YY	C16
1	IO_L27P_YY	F15
1	IO_L28N	G15
1	IO_L28P	D16
1	IO_L29N_YY	E16
1	IO_L29P_YY	A17
1	IO_L30N_YY	C17
1	IO_L30P_YY	E17
1	IO_L31N_Y	F16
1	IO_L31P_Y	D17
1	IO_L32N_YY	F17
1	IO_L32P_YY	C18
1	IO_L33N_YY	A18
1	IO_VREF_L33P_YY	G16
1	IO_L34N_YY	C19
1	IO_L34P_YY	G17
1	IO_L35N_Y	D18
1	IO_VREF_L35P_Y	B19[2]
1	IO_L36N_Y	D19
1	IO_L36P_Y	E18
1	IO_L37N_YY	F18
1	IO_L37P_YY	B20
1	IO_L38N_YY	G19
1	IO_VREF_L38P_YY	C20
1	IO_L39N_YY	G18
1	IO_L39P_YY	E19
1	IO_L40N_YY	A21

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
5	IO_L129N_Y	AB9
5	IO_L130P_YY	AA9
5	IO_L130N_YY	AF6
5	IO_L131P_YY	AC8
5	IO_VREF_L131N_YY	AC7
5	IO_L132P_YY	AD6
5	IO_L132N_YY	Y9
5	IO_L133P_YY	AE5
5	IO_L133N_YY	AA8
5	IO_L134P_YY	AC6
5	IO_VREF_L134N_YY	AB8
5	IO_L135P_YY	AD5
5	IO_L135N_YY	AA7
5	IO_L136P_Y	AF4
5	IO_L136N_Y	AC5
6	IO	P3
6	IO	AA3
6	IO	AC1[1]
6	IO	P1[1]
6	IO	R2[1]
6	IO	T1[1]
6	IO	V1[1]
6	IO	W3
6	IO	Y2
6	IO	Y6
6	IO_L137N_YY	AA5
6	IO_L137P_YY	AC3
6	IO_L138N_YY	AC2
6	IO_L138P_YY	AB4
6	IO_L139N_Y	W6
6	IO_L139P_Y	AA4
6	IO_VREF_L140N_Y	AB3
6	IO_L140P_Y	Y5
6	IO_L141N_Y	AB2
6	IO_L141P_Y	V7
6	IO_L142N_YY	AB1
6	IO_L142P_YY	Y4
6	IO_VREF_L143N_YY	V5
6	IO_L143P_YY	W5
6	IO_L144N_YY	AA1
6	IO_L144P_YY	V6
6	IO_L145N_Y	W4
6	IO_L145P_Y	Y3
6	IO_VREF_L146N_Y	Y1[2]
6	IO_L146P_Y	U7
6	IO_L147N_YY	W1
6	IO_L147P_YY	V4
6	IO_L148N_YY	W2
6	IO_VREF_L148P_YY	U6
6	IO_L149N_YY	V3
6	IO_L149P_YY	T5
6	IO_L150N_YY	U5
6	IO_L150P_YY	U4
6	IO_L151N_Y	T7
6	IO_L151P_Y	U3
6	IO_L152N_Y	U2
6	IO_L152P_Y	T6
6	IO_L153N_Y	U1
6	IO_L153P_Y	T4
6	IO_L154N_Y	R7
6	IO_L154P_Y	T3
6	IO_VREF_L155N_YY	R4
6	IO_L155P_YY	R6
6	IO_L156N_YY	R3
6	IO_L156P_YY	R5
6	IO_L157N_Y	P8
6	IO_L157P_Y	P7
6	IO_VREF_L158N_Y	R1
6	IO_L158P_Y	P6
6	IO_L159N_YY	P5
6	IO_L159P_YY	P4
7	IO	D1[1]

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	NC	L2
NA	NC	F6
NA	NC	F25
NA	NC	F21
NA	NC	F2
NA	NC	C26
NA	NC	C25
NA	NC	C2
NA	NC	C1
NA	NC	B6
NA	NC	B26
NA	NC	B24
NA	NC	B21
NA	NC	B16
NA	NC	B11
NA	NC	B1
NA	NC	AF25
NA	NC	AF24
NA	NC	AF2
NA	NC	AE6
NA	NC	AE3
NA	NC	AE26
NA	NC	AE24
NA	NC	AE21
NA	NC	AE16
NA	NC	AE14
NA	NC	AE11
NA	NC	AE1
NA	NC	AD25
NA	NC	AD2
NA	NC	AD1
NA	NC	AA6
NA	NC	AA25
NA	NC	AA21
NA	NC	AA2
NA	NC	A3
NA	NC	A25

Table 20: **FG676 — XCV400E, XCV600E**

Bank	Pin Description	Pin #
NA	NC	A2
NA	NC	A15
NA	VCCINT	G7
NA	VCCINT	G20
NA	VCCINT	H8
NA	VCCINT	H19
NA	VCCINT	J9
NA	VCCINT	J10
NA	VCCINT	J11
NA	VCCINT	J16
NA	VCCINT	J17
NA	VCCINT	J18
NA	VCCINT	K9
NA	VCCINT	K18
NA	VCCINT	L9
NA	VCCINT	L18
NA	VCCINT	T9
NA	VCCINT	T18
NA	VCCINT	U9
NA	VCCINT	U18
NA	VCCINT	V9
NA	VCCINT	V10
NA	VCCINT	V11
NA	VCCINT	V16
NA	VCCINT	V17
NA	VCCINT	V18
NA	VCCINT	Y7
NA	VCCINT	Y20
NA	VCCINT	W8
NA	VCCINT	W19
0	VCCO	J13
0	VCCO	J12
0	VCCO	H9
0	VCCO	H12
0	VCCO	H11

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
4	IO_VREF_L132P_YY	AV8
4	IO_L132N_YY	AU9
4	IO_L133P_Y	AW8
4	IO_L133N_Y	AT10
4	IO_VREF_L134P_Y	AV9[3]
4	IO_L134N_Y	AU10
4	IO_L135P_YY	AW9
4	IO_L135N_YY	AT11
4	IO_VREF_L136P_YY	AV10
4	IO_L136N_YY	AU11
4	IO_L137P_Y	AW10
4	IO_L137N_Y	AU12
4	IO_L138P_Y	AV11
4	IO_L138N_Y	AT13
4	IO_VREF_L139P_YY	AW11
4	IO_L139N_YY	AU13
4	IO_L140P_YY	AT14
4	IO_L140N_YY	AV12
4	IO_L141P_Y	AU14
4	IO_L141N_Y	AW12
4	IO_L142P_Y	AT15
4	IO_L142N_Y	AV13
4	IO_L143P_YY	AU15
4	IO_L143N_YY	AW13
4	IO_VREF_L144P_YY	AV14[1]
4	IO_L144N_YY	AT16
4	IO_L145P_Y	AW14
4	IO_L145N_Y	AU16
4	IO_L146P_Y	AV15
4	IO_L146N_Y	AR17
4	IO_L147P_YY	AW15
4	IO_L147N_YY	AT17
4	IO_VREF_L148P_YY	AU17
4	IO_L148N_YY	AV16
4	IO_L149P_Y	AR18
4	IO_L149N_Y	AW16

Table 22: **FG680 - XCV600E, XCV1000E, XCV1600E, XCV2000E**

Bank	Pin Description	Pin #
4	IO_L150P_Y	AT18
4	IO_L150N_Y	AV17
4	IO_L151P_YY	AU18
4	IO_L151N_YY	AW17
4	IO_VREF_L152P_YY	AT19
4	IO_L152N_YY	AV18
4	IO_L153P_Y	AU19
4	IO_L153N_Y	AW18
4	IO_VREF_L154P	AU21[2]
4	IO_L154N	AV19
4	IO_LVDS_DLL_L155P	AT21
5	GCK1	AU22
5	IO	AT34
5	IO	AW20
5	IO_LVDS_DLL_L155N	AT22
5	IO_VREF_L156P_Y	AV20[2]
5	IO_L156N_Y	AR22
5	IO_L157P_YY	AV23
5	IO_VREF_L157N_YY	AW21
5	IO_L158P_YY	AU23
5	IO_L158N_YY	AV21
5	IO_L159P_Y	AT23
5	IO_L159N_Y	AW22
5	IO_L160P_Y	AR23
5	IO_L160N_Y	AV22
5	IO_L161P_YY	AV24
5	IO_VREF_L161N_YY	AW23
5	IO_L162P_YY	AW24
5	IO_L162N_YY	AU24
5	IO_L163P_Y	AW25
5	IO_L163N_Y	AT24
5	IO_L164P_Y	AV25
5	IO_L164N_Y	AU25
5	IO_L165P_YY	AW26
5	IO_VREF_L165N_YY	AT25[1]

Table 29: **FG1156 Differential Pin Pair Summary: XCV1000E, XCV1600E, XCV2000E, XCV2600E, XCV3200E**

		P	N		Other
Pair	Bank	Pin	Pin	AO	Functions
153	3	AD31	AF33	3200 2600 2000 1600 1000	VREF
154	3	AC28	AF31	3200 2600 1600 1000	-
155	3	AC27	AF32	3200 2600 1600	-
156	3	AE29	AD28	2600 1000	VREF
157	3	AD30	AG32	3200 2600 2000 1600 1000	-
158	3	AC26	AH33	2000 1600	-
159	3	AD26	AF30	3200 2600 2000 1600 1000	VREF
160	3	AC25	AH32	2600 2000 1000	-
161	3	AE28	AL34	3200 2600 2000	-
162	3	AG30	AD27	3200 2600 1600 1000	-
163	3	AF29	AK34	3200 2600 2000 1600 1000	-
164	3	AD25	AE27	3200 2600 2000 1600	-
165	3	AJ33	AH31	2600 2000 1000	VREF
166	3	AE26	AL33	3200 2600 1600 1000	-
167	3	AF28	AL32	2600 1600	-
168	3	AJ31	AF27	3200 2600 1600 1000	VREF
169	3	AG29	AJ32	2600 2000 1000	-
170	3	AK33	AH30	3200 2600 2000	-
171	3	AK32	AK31	3200 2600 2000 1600 1000	INIT
172	4	AP31	AK29	3200 2600 2000 1600 1000	-
173	4	AP30	AN31	3200 1600 1000	-
174	4	AH27	AN30	3200 2000 1000	-
175	4	AM30	AK28	3200 2000 1000	VREF
176	4	AG26	AN29	3200 2600 1000	-
177	4	AF25	AM29	3200 2600 2000 1600 1000	-
178	4	AL29	AL28	3200 2600 2000 1600 1000	VREF
179	4	AE24	AN28	2000 1600	-
180	4	AJ27	AH26	3200 1000	-
181	4	AG25	AK27	3200 1000	-
182	4	AM28	AF24	3200 2600	-
183	4	AJ26	AP27	3200 2600 2000 1600 1000	-
184	4	AK26	AN27	3200 2600 2000 1600 1000	VREF
185	4	AE23	AM27	3200 1600	-
186	4	AL26	AP26	3200 2000 1000	-
187	4	AN26	AJ25	3200 2000 1000	VREF
188	4	AG24	AP25	3200 2600	-
189	4	AF23	AM26	3200 2600 2000 1600 1000	-
190	4	AJ24	AN25	3200 2600 2000 1600 1000	VREF
191	4	AE22	AM25	2600 1600 1000	-